

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re		Group Art Unit:	2812
Appln. of:	Uwe SCHWARZ		
Serial No.:	10/537,211	Conf. No.:	1865
Filed:	March 20, 2006	Examiner:	Reema PATEL
For:	PRODUCTION OF MICROELECTROMECHANICAL SYSTEMS (MEMS) USING THE HIGH-TEMPERATURE SILICON FUSION BONDING OF WAFERS	Atty Docket No.:	D4695-00135

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sirs:

Applicant submits this Supplemental Information Disclosure Statement pursuant to 37 C.F.R. §1.56. U.S. Patent No. 6,012,336 was first cited in a parallel European application. The required fee of \$180.00 charged to Deposit Account 04-1679 (Atty Docket No. D4695-00135) is submitted herewith via EFS charge authorization.

Respectfully submitted,

Dated: July 3, 2006

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